

Errata of changes for 2009 ITRS Executive Summary

Interconnect table now shows 16nm as the feature size.

Executive Summary Acknowledgments were updated to correct formatting issues, add to the acknowledgments for

Table of Contents were corrected to indicate proper level of a sub-section under Process Integration.

IITWG Tables' numbers were corrected as follows:

Original	Correct	
		Major Product Market Segments and Impact on System Drivers
Table ITWG1	Table ITWG1	
		Overall Design Technology Challenges
Table ITWG2	Table ITWG2	
		Summary of Key Test Drivers, Challenges, and Opportunities
Table ITWG3	Table ITWG3	
		Process Integration Difficult Challenges.
Table ITWG3	Table ITWG4	
		RF and Analog Mixed-Signal (RF and AMS) Technologies for Wireless
Table ITWG4	Table ITWG5	Communications Difficult Challenges
		Emerging Research Devices Difficult Challenges
Table ITWG5	Table ITWG6	
		Emerging Research Material Technologies Difficult Challenges
Table ITWG6	Table ITWG7	
		Front End Processes Difficult Challenges
Table ITWG7	Table ITWG8	
		Lithography Difficult Challenges >22 nm
Table ITWG8A	Table ITWG9A	
		Lithography Difficult Challenges ≤22 nm
Table ITWG8B	Table ITWG9B	
		Interconnect Difficult Challenges
Table ITWG9	Table ITWG10	
		Factory Integration Difficult Challenges
Table ITWG10	Table ITWG11	
		Assembly and Packaging Difficult Challenges
Table ITWG11	Table ITWG12	
		Environment, Safety, and Health Difficult Challenges—Near-term
Table ITWG12A	Table ITWG13A	
		Environment, Safety, and Health Difficult Challenges—Long-term
Table ITWG12B	Table ITWG13B	
		Yield Enhancement Difficult Challenges
Table ITWG13	Table ITWG14	
		Metrology Difficult Challenges
Table ITWG14	Table ITWG15	
		Modeling and Simulation Difficult Challenges
Table ITWG15	Table ITWG16	

Assembly and Packaging summary was updated